

Potting Epoxy

This is a two part, unfilled, electronic grade epoxy encapsulant, designed for medium sized castings. It cures at room temperature to a tough, semi-rigid polymer. It has good wetting and adhesion to most surfaces. It is free flowing to penetrate voids and give good air release, with a smooth high gloss surface. It has very good resistance to water, acids and bases, and most organic solvents. It was formulated to a 1A:1B volume mix ratio, for use in side-by-side dispensing cartridges and meter/mix and dispense equipment. It will reach full cure at room temperature within 24 hours. Cure time can be accelerated by the application of heat, after product has gelled. Times and temperatures from 1 hour at 65 °C to 20 minutes at 110 °C are typical for small castings (less than 50 grams). 24 hours at room temperature.

FEATURES:

- Hardness: 80 Shore D
- Viscosity - Mixed: 11,000 cps
- Pot Life: 15-20 minutes/50g sample
- (-40 to 300)°F Temperature Range
- 3.5 Dielectric Constant
- 410 V/mil Dielectric Strength
- 12 Month Shelf Life

BENEFITS:

- Tensile Strength : 8,500 psi
- Compressive Strength : 22,000 psi
- Lap Shear Strength : 1,500 psi
- Water Absorption : 0.18% after 24 hours
- Specific Gravity - Mixed : 1.07

Clean up uncured resin with suitable organic solvent such as MEK, acetone or other organic solvent.

Product Details:

PART No.	TYPE	SIZE
19-823	(2) Bottles Plastic	(2) 4 oz.

**PART No:** **19-823**

Country of Origin: USA
UPC: 010151134349
HTS: 3506.10.0000